Characteristics ESDAL

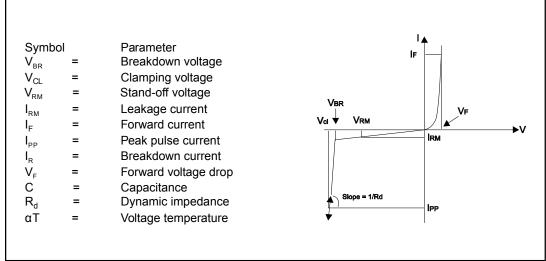
1 Characteristics

Table 1: Absolute maximum ratings (T_{amb} = 25 °C)

Symbol	Parameter	Value	Unit		
		IEC 61000-4-2:			
V_{pp}	Peak pulse voltage ⁽¹⁾	Contact discharge	30	kV	
		Air discharge	30		
P_{pp}	Peak pulse power (8/20 µs)	300	W		
Ірр	Peak pulse current (8/20 μs)	ESDA5V3L	25		
		ESDA6V1L	18		
		ESDA14V2L	14	Α	
		ESDA25L	7		
		ESDA37L	6.3		
Tj	Operating junction temperature range	-40 to 150	°C		
T _{stg}	Storage junction temperature range	-65 to 150	°C		
TL	Maximum lead temperature for soldering during 10 s at 5 mm from case 260				

Notes:

Figure 2: Electrical characteristics (definitions)



⁽¹⁾For a surge greater than the maximum values, the diode will fail in short-circuit.

ESDAL Characteristics

Table 2: Electrical characteristics (T_{amb} = 25 °C)

	V _{BR} at I _R		I _{RM} at V _{RM}		R _d ⁽¹⁾	αT ⁽²⁾	Cline	V _F at I _F		
Order code	Min.	Max.		Max.		Тур.	Max.	Typ. at 0 V bias	Max.	
	V	V	mA	μΑ	V	mΩ	10 ⁻⁴ /°C	pF	V	mA
ESDA5V3L	5.3	5.9	1	2	3	280	5	220	1.25	200
ESDA6V1L	6.1	7.2	1	20	5.25	350	6	140	1.25	200
ESDA14V2L	14.2	15.8	1	5	12	650	10	90	1.25	200
ESDA25L	25	30	1	1	24	1000	10	50	1.2	10
ESDA37L	37	43.3	1	1	36	2400	10	48	0.9	10

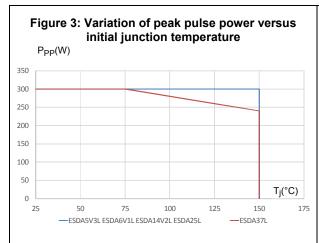
Notes:

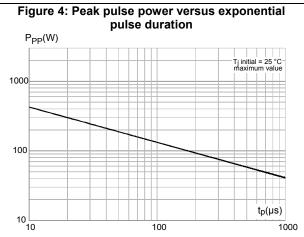
 $^{^{(1)}} Square$ pulse I_{pp} = 15 A, t_{p} = 2.5 μs

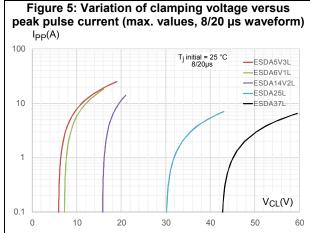
 $^{^{(2)}\}Delta$ V_{BR} = α T x (T_{amb} -25 °C) x V_{BR} (25 °C)

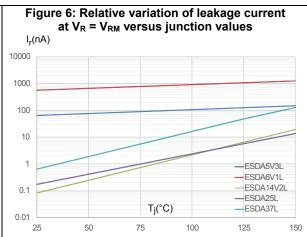
Characteristics ESDAL

1.1 Characteristics (curves)









2 Application and design guidelines

Refer to STMicroelectronics application note:

 AN2689: Protection of automotive electronics from electrical hazards, guidelines for design and component selection.



Package information ESDAL

3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

- Epoxy meets UL 94,V0
- Lead-free package

3.1 SOT23-3L mechanical data

Pigure 7: SO123-3L package outline

D

e1

e1

e1

s

cucr Plane

SLAING PLANE

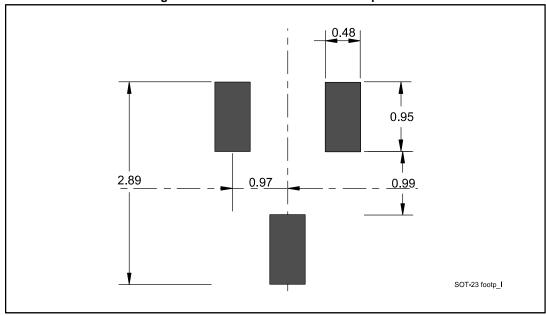
Figure 7: SOT23-3L package outline

005 3390_I

Table 3: SOT23-3L mechanical data

	mm					
Dim.	mm					
5	Min.	Тур.	Max.			
Α	0.89	0.89				
A1	0		0.10			
В	0.30	0.51				
С	0.085	0.18				
D	2.75		3.04			
е	0.85		1.05			
e1	1.70		2.10			
Е	1.20		1.75			
Н	2.10		3.00			
L	0.60					
S	0.35 0.		0.65			
L1	0.25		0.55			
а	0° 8°					

Figure 8: SOT23-3L recommended footprint





Dimensions are in mm.

4 Recommendation on PCB assembly

4.1 Solder paste

- 1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
- 2. "No clean" solder paste is recommended.
- 3. Offers a high tack force to resist component movement during high speed.
- 4. Use solder paste with fine particles: powder particle size 20-45 μm.

4.2 Placement

- 1. Manual positioning is not recommended.
- 2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering
- Standard tolerance of ±0.05 mm is recommended.
- 4. 3.5 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
- 5. To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
- 6. For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

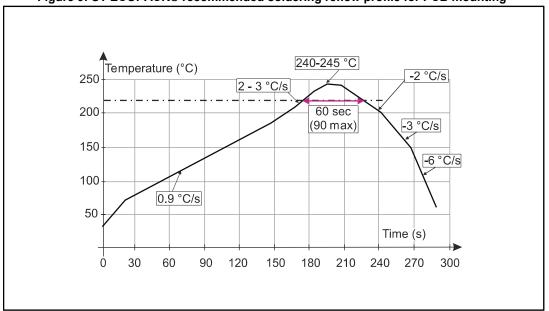
4.3 PCB design preference

- 1. To control the solder paste amount, the closed via is recommended instead of open vias.
- 2. The position of tracks and open vias in the solder area should be well balanced. A symmetrical layout is recommended, to avoid any tilt phenomena caused by asymmetrical solder paste due to solder flow away.



4.4 Reflow profile

Figure 9: ST ECOPACK® recommended soldering reflow profile for PCB mounting





Minimize air convection currents in the reflow oven to avoid component movement.

Ordering information ESDAL

5 Ordering information

Figure 10: Ordering information scheme

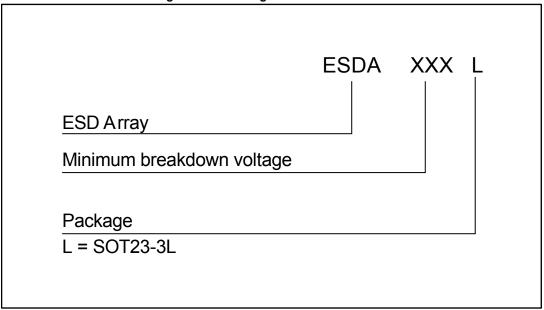


Table 3: Ordering information

Order code	Marking ⁽¹⁾	Package	Weight	Base qty.	Delivery mode
ESDA5V3L	EL53				
ESDA6V1L	EL61	SOT23-3L	0.7		
ESDA14V2L	EL15		8.7 mg	3000	Tape and reel
ESDA25L	EL25				
ESDA37L	EL37		9.8 mg		

Notes:

6 Revision history

Table 4: Document revision history

Date	Revision	Changes
31-Jul-2012	4	First issue.
20-Jul-2017	5	Added ESDA37L package information.

 $^{^{(1)}}$ The marking can be rotated by multiples of 90° to differentiate assembly location.

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